

TGF25-FG

Leader Tech's TGF25 thermal gap filler with a fiberglass carrier, has excellent flexibility and compressibility. The material is used to fill gaps and assist in heat transfer between components. Thermal gap filler provides insulation and shock mitigation effects while satisfying the design requirements for ultra-thin equipment with excellent manufacturability, practicability and a wide range of thicknesses.

Features:

- Soft, excellent compression performance
- Excellent compression rate
- Low thermal impedance
- Viscous surface
- UL94 V-0 recognized
- Excellent electrical insulation performance and heat resistance
- RoHS and Halogen Compliant

Applications:

- Between chip and heat-dissipation modules
- Optoelectronics industry
- Netcom products
- New energy Battery and Automotive Industry
- Household Appliances
- Wearable Technology

Storage Conditions:

- Store in the darkness
- Storage Temperature: $\leq 30^{\circ}\text{C}$
- Storage Humidity: $\leq 70\%$
- When stacking the parts, the parts should not be higher than 7 layers or more than 1m

Shelf Life:

- Stored at storage conditions: Two years
- Stored in unqualified storage conditions: 6 months

Properties:

Item	Parameter	Unit	Test Method
Color	Light Yellow	-	Visual
Carriers	Fiberglass cloth	-	-
Thickness	0.012 ~ 0.710	in	ASTM D374
Hardness	10~55(±5)	Shore C	ASTM D2240
Density	2.6(±0.5)	g/cc	ASTM D792
Tensile Strength	≥0.2	Mpa	ASTM D412
Elongation	≥70	%	ASTM D412
Compression Ratio	≥20(@50PSI)	%	ASTM D695
UL Certification	V-0, 5V	-	UL94
Operating Temperature	-50 to 180	°C	IEC 600068-2-14

Thermal Characteristics:

Thermal Conductivity	2.5(±0.2)	W / m·K	ASTM D5470
Thermal Resistance	≤1.0(@20PSI/1mm)	°Cin ² /W	ASTM D5470

Electrical Properties:

Breakdown Voltage	≥8	KV/mm	ASTM D149
Volume Resistivity	≥10 ¹⁰	Ω·cm	ASTM D257
Dielectric constant	≥2	@1MHz	ASTM D150
Dielectric loss	≤0.1	@1MHz	ASTM D150

Global EMI Shielding Technology Center
12420 Race Track Rd., Tampa, Florida 33626
866.TECH.EMI (866.832.4364) † 813.855.6921 ‡ 813.855.3291

www.LeaderTechInc.com



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